



GP
ELECTRONICS

GPM300ND06LNB
60V Dual N-Channel MOSFET

Product Summary

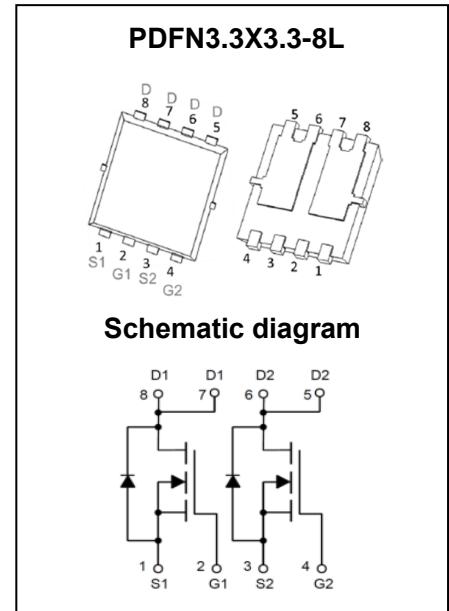
V _{(BR)DSS}	R _{D(on)TYP}	I _D
60V	25mΩ@10V	20A
	34mΩ@4.5V	

Feature

- Trench Technology Power MOSFET
- Low R_{D(on)}
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- Power Switching Application



MARKING:



M300ND06L = Device Code

XX = Date Code

Solid Dot = Green Indicator

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

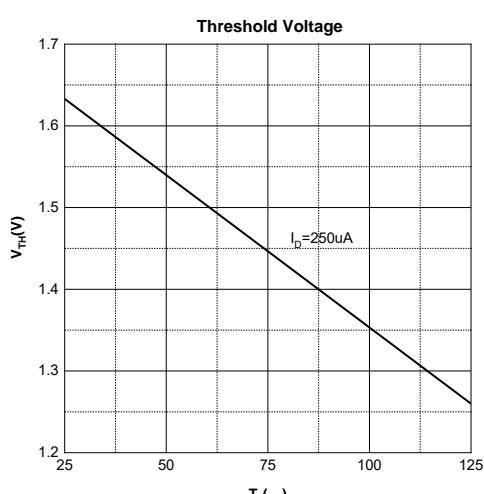
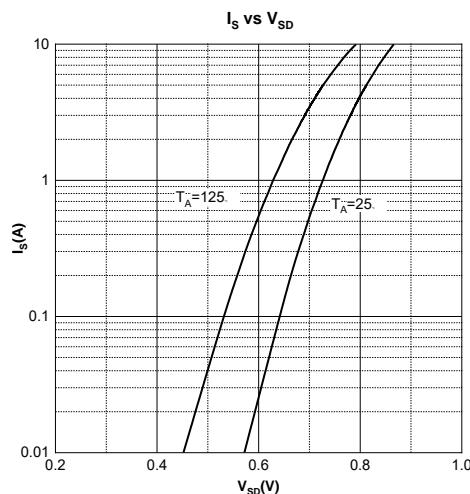
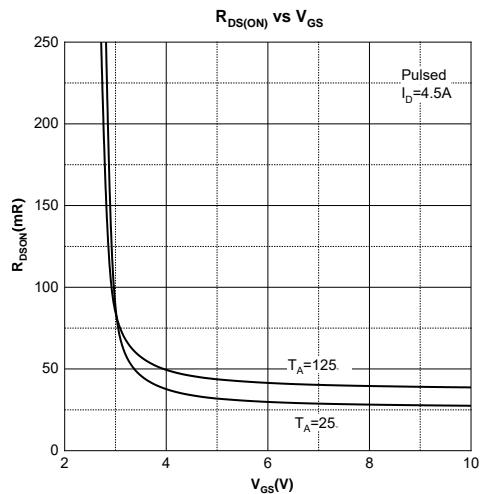
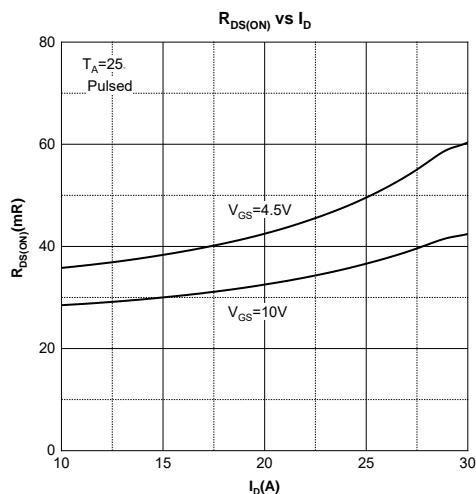
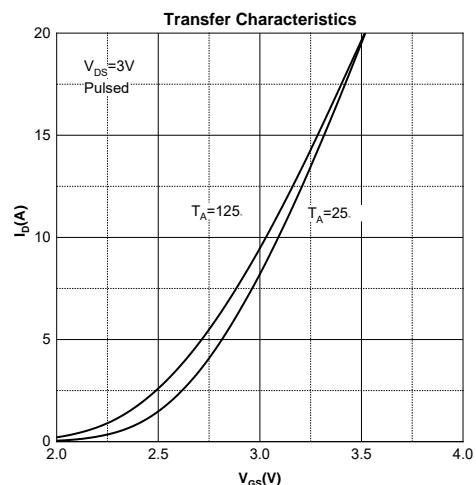
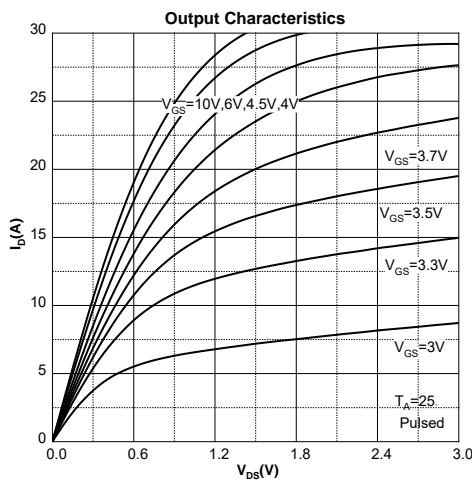
Parameter	Symbol	Value	Unit
Drain - Source Voltage	V _{DS}	60	V
Gate - Source Voltage	V _{GS}	±20	V
Continuous Drain Current ¹	T _C = 25°C	I _D	A
	T _C = 60°C	I _D	A
Pulsed Drain Current ²	I _{DM}	80	A
Single Pulsed Avalanche Current ³	I _{AS}	12	A
Single Pulsed Avalanche Energy ³	E _{AS}	40	mJ
Power Dissipation ⁵	T _C = 25°C	P _D	W
Thermal Resistance from Junction to Ambient ⁶		R _{θJA}	°C/W
Thermal Resistance from Junction to Case	R _{θJC}	5.5	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55~+150	°C

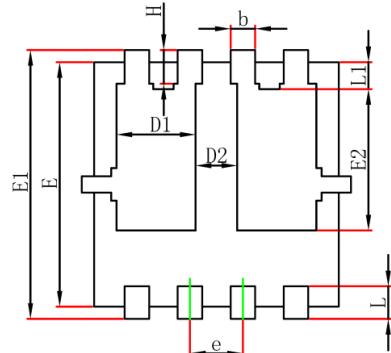
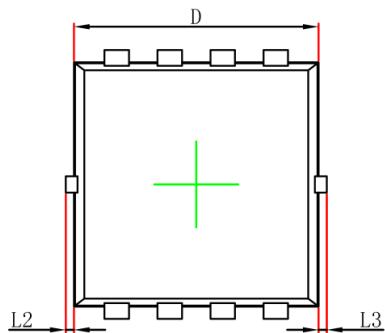
MOSFET ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	60			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 60V, V_{GS} = 0V$			1	μA
Gate - Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
On Characteristics⁴						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1	1.8	3	V
Drain-source On-resistance	$R_{DS(\text{on})}$	$V_{GS} = 10V, I_D = 4.5A$		25	42	$\text{m}\Omega$
		$V_{GS} = 4.5V, I_D = 4A$		34	52	
Forward Transconductance	g_{FS}	$V_{DS} = 10V, I_D = 10A$		16		S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = 30V, V_{GS} = 0V, f = 1\text{MHz}$		894		pF
Output Capacitance	C_{oss}			70		
Reverse Transfer Capacitance	C_{rss}			59		
Gate Resistance	R_g	$V_{DS} = 0V, V_{GS} = 0V, f = 0.1\text{MHz}$		1.6		Ω
Switching Characteristics						
Total Gate Charge	Q_g	$V_{DS} = 30V, V_{GS} = 10V, I_D = 4.5A$		21		nC
Gate-source Charge	Q_{gs}			2.5		
Gate-drain Charge	Q_{gd}			5.4		
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{DD} = 30V, V_{GS} = 10V, I_D = 10A, R_G = 3\Omega$		7		ns
Turn-on Rise Time	t_r			17		
Turn-off Delay Time	$t_{d(\text{off})}$			27		
Turn-off Fall Time	t_f			8		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$V_{GS} = 0V, I_s = 1.7A$			1.2	V

Notes :

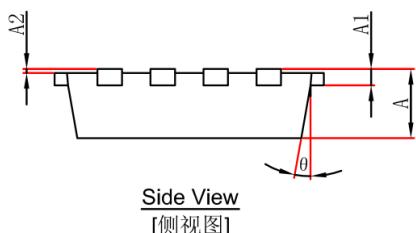
- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu\text{s}$, duty cycle $\leq 1\%$.
- 3.E_{AS} condition: $V_{DD} = 30V, V_{GS} = 10V, L = 0.5\text{mH}, R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(\text{MAX})} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Characteristics


PDFN3.3X3.3-8L Package Information


Top View
[顶视图]

Bottom View
[背视图]



Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.152REF		0.006REF	
A2	0.000	0.050	0.000	0.002
D	2.900	3.200	0.114	0.126
D1	0.935	1.135	0.037	0.045
D2	0.280	0.480	0.011	0.019
E	2.900	3.200	0.114	0.126
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0.000	0.100	0.000	0.004
L3	0.000	0.100	0.000	0.004
H	0.315	0.515	0.012	0.020
θ	0°	12°	0°	12°